

(19)



JAPANESE PATENT OFFICE

BEST AVAILABLE COPY

## PATENT ABSTRACTS OF JAPAN

(11) Publication number: 62119952 A

(43) Date of publication of application: 01.06.87

(51) Int. Cl

H01L 25/04

(21) Application number: 60259972

(71) Applicant: NEC CORP

(22) Date of filing: 19.11.85

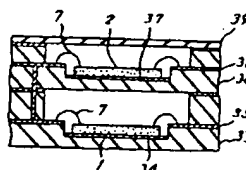
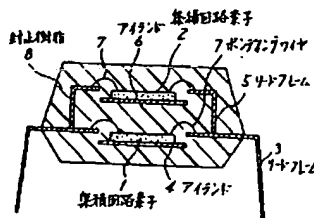
(72) Inventor: MITANI HITOSHI

## (54) INTEGRATED CIRCUIT DEVICE

## (57) Abstract:

**PURPOSE:** To realize a device occupying but a small area by a method wherein an IC is installed on a lead frame and wiring is accomplished between them, another IC is installed on another lead frame and wiring is accomplished between them, the two lead frames are connected with each other, and the entirety is sealed in resin.

**CONSTITUTION:** An IC element 1 is installed on a first island 4 and connection is made to a lead frame 3 by a bonding wire 7. Next, an IC element 2 is installed on a second island 6 and connection is made to a lead frame 5 by a bonding wire 7. Finally, the lead frames 3 and 5 are connected and sealing is accomplished in resin 8 for the completion of the device. Another method may be employed wherewith IC elements are housed in ceramic packages instead of resin for the realization of a laminate of packages. A plurality of IC elements may be installed on a single lead frame.



COPYRIGHT: (C)1987,JPO&amp;Japio